

FULLY - AUTOMATED DIE BONDER

# T-6000

The **T-6000** Die Bonder is an all purpose system for R&D, pilot and medium size production. Die handling is standard from Wafer, Waffle-Pack and Gel-Pack. Automatic Die assembly utilizing pattern recognition is combined with ease of use operation and suited for manual single Die placement.

Automatic Die Bonding

Pattern recognition system

Step resolution 1  $\mu\text{m}$   
in all axis

Easy to use

MICRO ASSEMBLY

T-6000



# TRESKY

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Sophisticated accessories and rapid tool exchange grant high-precision bonding, outstanding flexibility and efficient automation.

The graphical intuitive interface makes the system easy to operate. Status overview at a glance and menu prompting provide immediate, simple access to all system functions.

### APPLICATIONS:

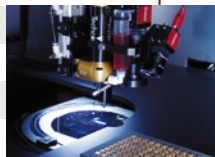
Die Attach, Die Sorting, Flip-Chip, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding, .....

### FEATURES AND OPTIONS:

Graphical User Interface: Java based, user optimized for Quick manual Pick & Place, semi automatic and automatic assembly with pattern recognition



- > Up looking camera
- > Dispensing & Stamping unit
- > Holder for Pick-Up tool
- > Tool magazine (for automatic exchange of the tools)
- > Eutectic bond unit
- > Customized substrate holder
- > Customized waffle pack holder
- > Wafer rings or wafer frames
- > Automatic 3-D calibration



### TECHNICAL DATA:

XY- Movement (placement stage):	400mm x 315mm (automatic: 1µm resolution)
XY- Movement (wafer stage):	220mm x 220mm (automatic: 1µm resolution)
Z- Movement:	100mm (automatic: 1µm resolution)
Spindle Rotation:	360°(automatic; angle resolution: ±0.001°)
Bond Force (standard range):	15g - 800g (programmable via spring load)
Throughput:	600 to 900 dies/h (typical value, for standard appl. utilizing pick & place system)
Placement accuracy:	±7 µm
Connections:	Compressed air 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	1155mm x 910mm x 1530mm
Weight:	450kg (approx.)
Voltage:	220V-260V, 50Hz, 2.3kW single line

Note: All specifications are subject to change without notice

### REPRESENTED BY:

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